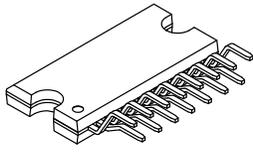


# MECHANICAL CASE OUTLINE

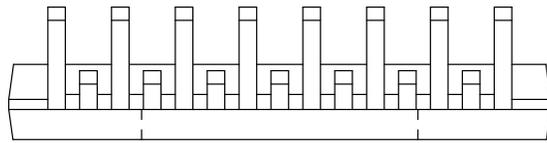
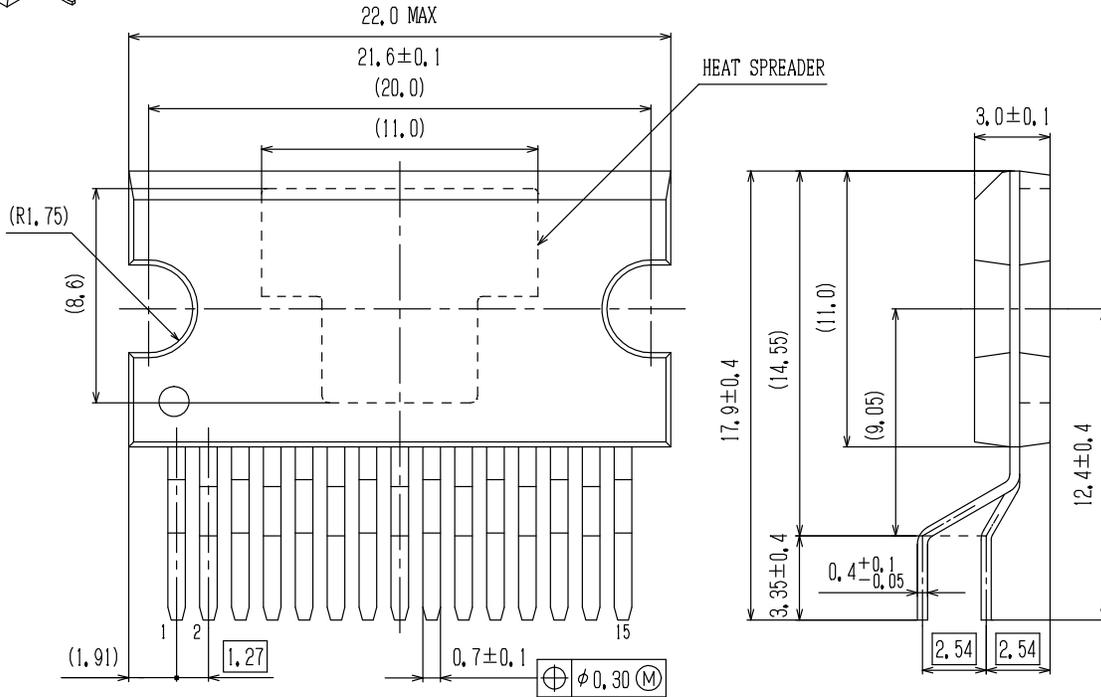
## PACKAGE DIMENSIONS

ON Semiconductor®



**HZIP15**  
CASE 945AB  
ISSUE A

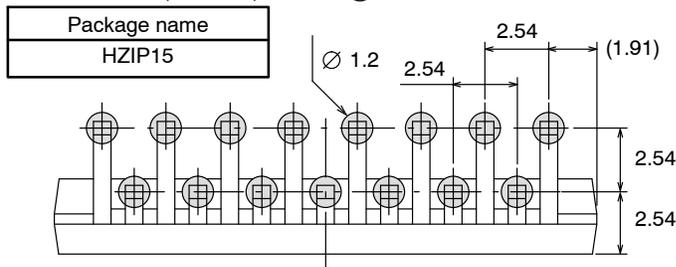
DATE 24 OCT 2013



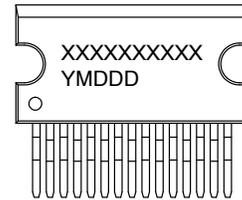
**SOLDERING FOOTPRINT\***

(Unit: mm)

○ Through Hole Area



### GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code

Y = Year

M = Month

DDD = Additional Traceability Data

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>HZIP15</b>	<b>PAGE 1 OF 1</b>

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